



## Material Content Data Sheet



<b>Sales Product Name</b>		BAS 16-02L E6327		<b>Issued</b>		30. January 2015		
<b>MA#</b>		MA000100801						
<b>Package</b>		PG-TSLP-2-1		<b>Weight*</b>		0.52 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	non noble metal	tin	7440-31-5	0.001	0.10		1046	
	noble metal	gold	7440-57-5	0.002	0.41		4059	
	inorganic material	silicon	7440-21-3	0.026	4.96	5.47	49551	54656
leadframe	non noble metal	nickel	7440-02-0	0.100	19.42	19.42	194217	194217
wire	noble metal	gold	7440-57-5	0.005	1.04	1.04	10360	10360
encapsulation	inorganic material	antimonytrioxide	1309-64-4	0.000	0.04		353	
	organic material	carbon black	1333-86-4	0.004	0.70		7033	
	plastics	epoxy resin	-	0.049	9.50		94954	
	inorganic material	silicondioxide	60676-86-0	0.310	60.09	70.33	601022	703362
leadfinish	noble metal	gold	7440-57-5	0.010	1.87	1.87	18688	18688
plating	noble metal	gold	7440-57-5	0.010	1.87	1.87	18717	18717
*deviation	< 10%		Sum in total:			100.00		1000000

### Important Remarks:

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